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7 FLOOR-1, NO. 100  
ROOSEVELT ROAD, SECTION 2  
TAIPEI 100 TW TAIWAN

Paper No. 072506

*In re* Application of  
Chen et al.  
Application No.: 10/707,683  
Filed: January 5, 2004  
For: **CHIP PACKAGE STRUCTURE AND PROCESS FOR  
FABRICATING THE SAME**

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:  
: **WITHDRAWAL FROM ISSUE**  
: *37 CFR 1.313*  
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The purpose of this communication is to inform you that the above-identified application is being withdrawn from issue pursuant to 37 CFR 1.313.

The application is being withdrawn from issue because of unpatentability of at least one claim.

The US Patent and Trademark Office records reveal that the issue fee has not been paid. If the issue fee has been submitted, the applicant may request a refund, or may request that the fee be credited to a deposit account. However, applicant may wait until the application is either again found allowable or held abandoned. If the application is allowed, upon receipt of a new Notice of Allowance and Fee(s) Due, applicant may request that the previously submitted issue fee be applied toward payment of the issue fee in the amount identified on the new Notice of Allowance and Fee(s) Due. If the application is abandoned, applicant may request either a refund or a credit to a Deposit Account.

Any question regarding this communication should be directed to Bill Baumeister, Supervisory Patent Examiner, at (571) 272-1722.

The above-identified application is being forwarded to the examiner for prompt appropriate action, including notifying applicant of the new status of this application.

Sharon Gibson, Director  
Technology Center 2800  
Semiconductors, Electrical and Optical  
Systems and Components